

Bill of Materials

	SCM	SCC	Remarks
Die Attach	Hitachi EN4900	Hitachi EN4900	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Hitachi CEL9220	Hitachi CEL9220	
Lead Finish	NiPdAu	NiPdAu	

Qualification Results Summary for LFCSP Package in NiPdAu Pre-plated Leadframe at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Specifications	Sample Size	Result
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
Low Temperature Storage (LTS)	JEDEC <i>JESD22-A119</i>	3 x 77	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

Test Correlation Report

<u>FG Part Number</u>	<u>Test Correlation Status</u>
ADA4930-1SCPZ-EPR2	Pass
ADA4930-1SCPZ-EPR7	Pass
ADA4930-1SCPZ-EPRL	Pass
AD45203Z-RL	Pass
AD57/005Z-0RL	Pass
ADF7023BCPZ	Pass
ADF7023BCPZ-RL	Pass
ADP2384ACPZN-R7	Pass
ADP2386ACPZN-R7	Pass
ADF7024BCPZ	Pass
ADF7024BCPZ-RL	Pass